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Product Change Notification - KSRA-31LQPW108

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Date:

02 Jun 2018

Product Category:

8-bit PIC Microcontrollers

Affected CPNs:**Notification subject:**

CCB 3051 Final Notice: Qualification of ASE as an additional assembly site for selected Atmel products available in 100L TFBGA (9x9mm) package

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASE as an additional assembly site for selected Atmel products available in 100L TFBGA (9x9mm) package.

Pre Change:

Assembled at LPI assembly site

Post Change:

Assembled at LPI or ASE assembly site

Pre and Post Change Summary:

| | Pre Change | Post Change | |
|---------------|---|---|----------------|
| Assembly Site | Lingsen Precision Industires, LTD. (LPI) | Lingsen Precision Industires, LTD. (LPI) | ASE Inc. (ASE) |

| | | | |
|----------------------------------|---------------|---------------|---------------|
| Wire material | Au wire | Au wire | Au wire |
| Die attach material | 2100 | 2100 | 2100 |
| Molding compound material | G770H | G770H | KE-G1250NAS |
| Substrate material | HL832NX(A-HS) | HL832NX(A-HS) | HL832NX(A-HS) |
| Solder Ball | SAC 305 | SAC 305 | SAC 105 |

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying ASE as an additional assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

July 02, 2018 (date code: 1827)

Time Table Summary:

| Workweek | September 2017 | | | | | --> | June 2018 | | | | | July 2018 | | | | |
|-------------------------------|----------------|----|----|----|----|-----|-----------|----|----|----|----|-----------|----|----|----|----|
| | 35 | 36 | 37 | 38 | 39 | | 22 | 23 | 24 | 25 | 26 | 27 | 28 | 29 | 30 | 31 |
| Initial PCN Issue Date | | | | X | | | | | | | | | | | | |
| Qual Report Availability | | | | | | | X | | | | | | | | | |
| Final PCN Issue Date | | | | | | | X | | | | | | | | | |
| Estimated Implementation Date | | | | | | | | | | | | X | | | | |

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

September 18, 2017: Issued initial notification.

June 02, 2018: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on July 02, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-31LQPW108_Qual Report.pdf](#)

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